

**Features**

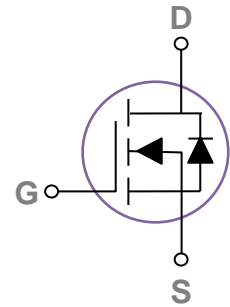
- 800V, 17A,  $R_{DS(ON)} = 0.35\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

**Applications**

- High efficient switched mode power supplies
- LED Lighting
- Adapter/charger



TO-220F



Schematic Diagram



**Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are suited for high efficiency fast switching applications.

**Absolute Maximum Ratings**  $T_C = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	800	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current – Continuous ( $T_C = 25^\circ C$ )	$I_D$	17	A
Drain Current – Continuous ( $T_C = 100^\circ C$ )		10.7	A
Drain Current – Pulsed <sup>1</sup>	$I_{DM}$	68	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	1014	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	4.2	A
Power Dissipation ( $T_C = 25^\circ C$ )	$P_D$	55	W
Power Dissipation – Derate above $25^\circ C$		0.44	W/ $^\circ C$
Storage Temperature Range	$T_{STG}$	-50 to 150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-50 to 150	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	-	62	$^\circ C/W$
Thermal Resistance Junction to Case	$R_{\theta JC}$	-	2.27	$^\circ C/W$

**Electrical Characteristics** ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)

**Off Characteristics**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	800	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.8	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=800V, V_{GS}=0V,$ $T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=640V, V_{GS}=0V,$ $T_J=85^\circ\text{C}$	---	---	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	100	nA

**On Characteristics**

Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	---	0.26	0.35	$\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.5	3.5	4.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-7.84	---	$\text{mV}/^\circ\text{C}$

**Dynamic and switching Characteristics**

Total Gate Charge <sub>3,4</sub>	$Q_g$	$V_{DS}=50V, V_{GS}=10V,$ $I_D=1.3A$	---	57.2	---	
Gate-Source Charge <sub>3,4</sub>	$Q_{gs}$		---	6.3	---	nC
Gate-Drain Charge <sub>3,4</sub>	$Q_{gd}$		---	27.4	---	
Turn-On Delay Time <sub>3,4</sub>	$T_{d(on)}$	$V_{DD}=30V, V_{GS}=10V,$ $R_G=6\Omega, I_D=0.5A$	---	80	---	
Rise Time <sub>3,4</sub>	$T_r$		---	70	---	
Turn-Off Delay Time <sub>3,4</sub>	$T_{d(off)}$		---	650	---	ns
Fall Time <sub>3,4</sub>	$T_f$		---	190	---	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $F=1\text{MHz}$	---	1650	---	
Output Capacitance	$C_{oss}$		---	580	---	pF
Reverse Transfer Capacitance	$C_{riss}$		---	25	---	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V,$ $F=1\text{MHz}$	---	1.36	---	$\Omega$

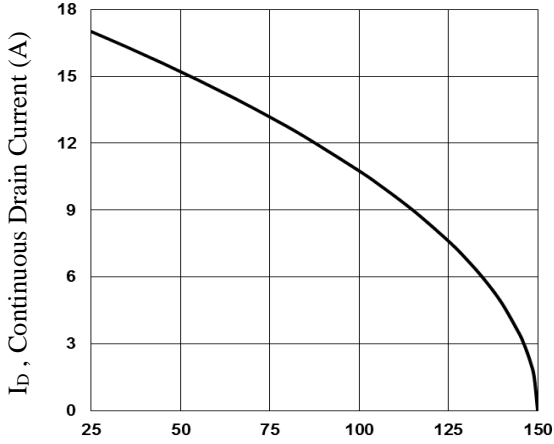
**Drain-Source Diode Characteristics and Maximum Ratings**

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_S$	$V_G=V_D=0V$ , Force Current	---	---	17	A
Pulsed Source Current	$I_{SM}$		---	---	34	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
Body Diode Reverse Recovery Time	$T_{rr}$	$I_S=13A, V_{GS}=0V$ $di/dt=100A/\mu S$	---	460	---	nS
Body Diode Reverse Recovery Charge	$Q_{rr}$		---	8.35	---	$\mu C$

Note :

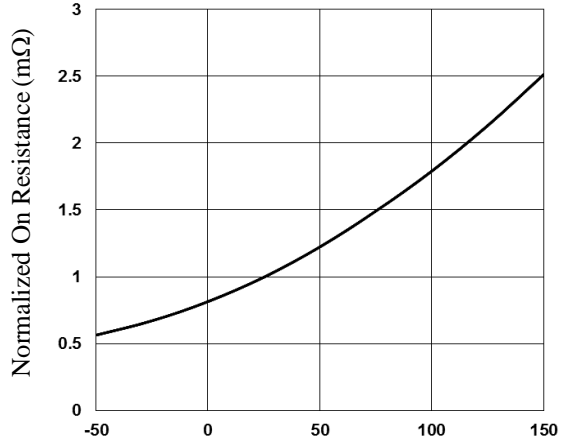
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.  
 $V_{DD}=25V, V_{GS}=10V, L=115\text{mH}, I_{AS}=4.2A, R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}.$
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

**Typical Electrical and Thermal Characteristics**



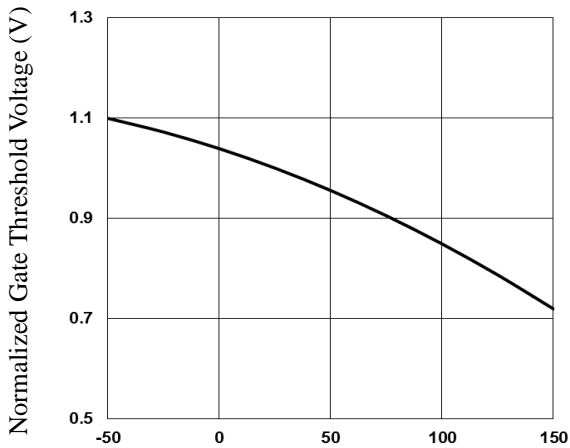
$T_C$ , Case Temperature ( $^{\circ}C$ )

**Fig.1 Continuous Drain Current vs.  $T_C$**



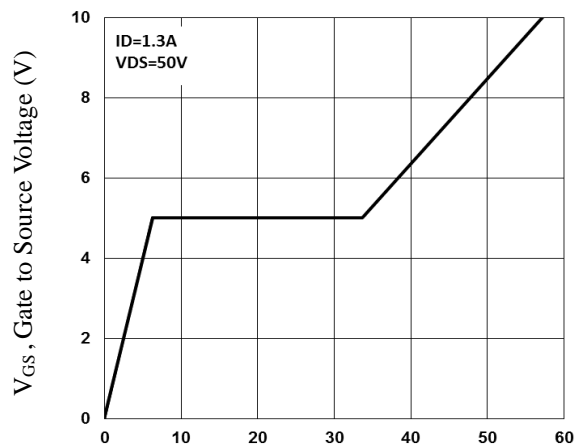
$T_J$ , Junction Temperature ( $^{\circ}C$ )

**Fig.2 Normalized RDSON vs.  $T_J$**



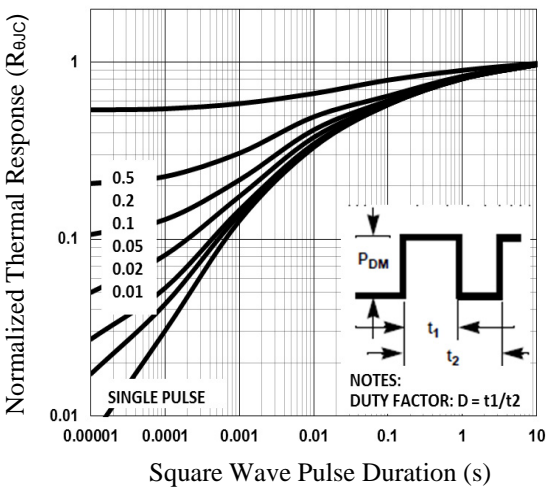
$T_J$ , Junction Temperature ( $^{\circ}C$ )

**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**

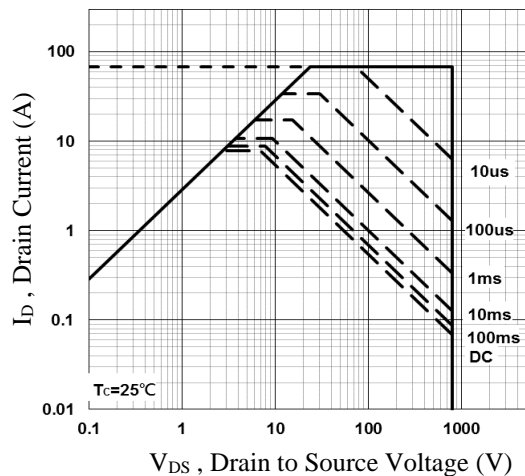


$Q_g$ , Gate Charge (nC)

**Fig.4 Gate Charge Characteristics**



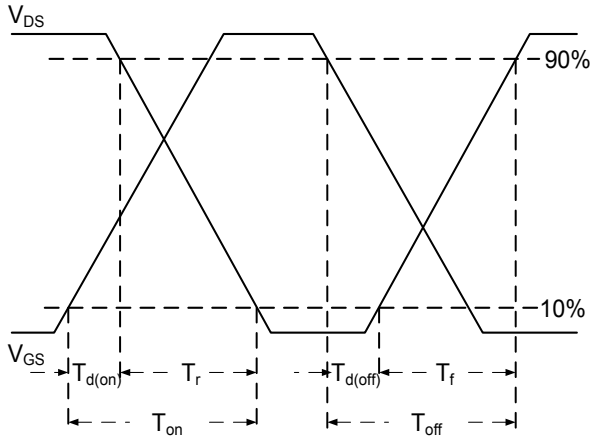
**Fig.5 Normalized Transient Impedance**



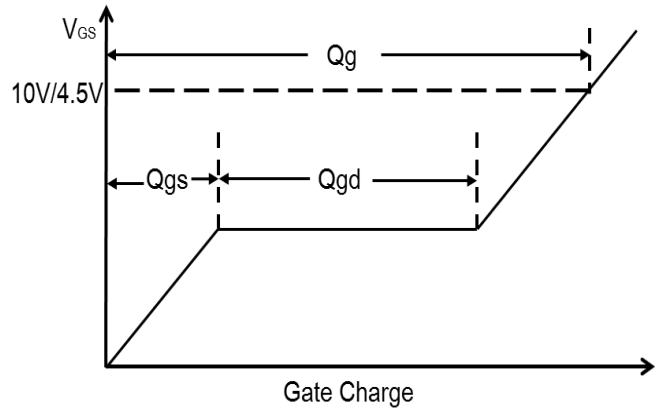
$V_{DS}$ , Drain to Source Voltage (V)

**Fig.6 Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristics**



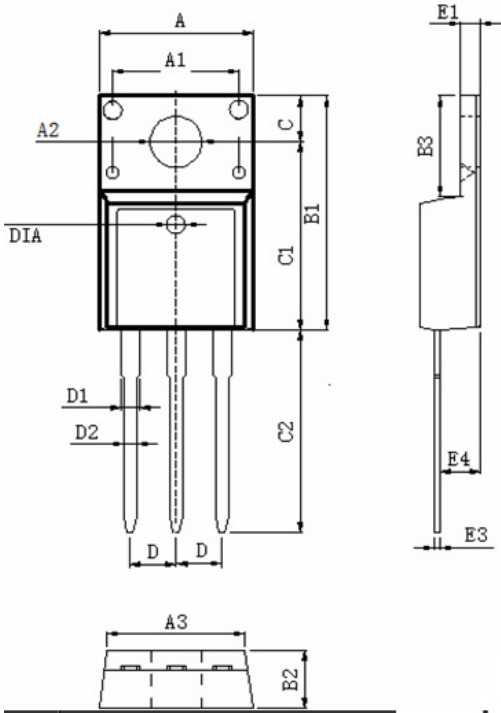
**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

**Package Outline Dimensions**

**TO-220F**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.460	9.860	0.412	0.388
A1	7.100	6.900	0.280	0.272
A2	3.500	3.100	0.138	0.122
A3	9.900	9.500	0.390	0.374
B1	16.170	15.570	0.637	0.613
B2	4.900	4.500	0.193	0.177
B3	6.880	6.480	0.271	0.255
C	3.500	3.100	0.138	0.122
C1	12.870	12.270	0.507	0.483
C2	13.380	12.580	0.527	0.495
D	2.590	2.490	0.102	0.098
D1	1.470	1.070	0.058	0.042
D2	0.900	0.700	0.035	0.028
E1	2.740	2.340	0.108	0.092
E3	0.600	0.400	0.024	0.016
E4	2.960	2.560	0.117	0.101
DIA	Φ1.5 TYP.	deep0.1 TYP.	Φ0.059 TYP.	deep0.004 TYP.